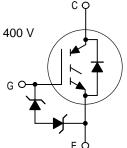
Designer's™ Data Sheet

Insulated Gate Bipolar Transistor with Anti-Parallel Diode

N-Channel Enhancement-Mode Silicon Gate

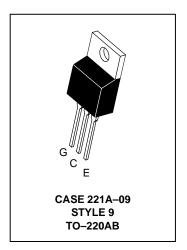
This Insulated Gate Bipolar Transistor (IGBT) is co–packaged with a soft recovery ultra–fast rectifier and uses an advanced termination scheme to provide an enhanced and reliable high voltage–blocking capability. Its new 600 V IGBT technology is specifically suited for applications requiring both a high temperature short circuit capability and a low $V_{CE(on)}$. It also provides fast switching characteristics and results in efficient operation at high frequencies. Co–packaged IGBTs save space, reduce assembly time and cost. This new E–series introduces an energy efficient, ESD protected and short circuit rugged device.

- Industry Standard TO–220 Package
- High Speed: E_{off} = 60 μJ/A typical at 125°C
- High Voltage Short Circuit Capability 10 μs minimum at 125°C, 400 V
- Low On-Voltage 2.0 V typical at 3.0 A, 125°C
- Soft Recovery Free Wheeling Diode is Included in the Package
- Robust High Voltage Termination
- ESD Protection Gate-Emitter Zener Diodes



MGP4N60ED

IGBT & DIODE IN TO-220 4.0 A @ 90°C 6.0 A @ 25°C 600 VOLTS SHORT CIRCUIT RATED LOW ON-VOLTAGE



MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCES	600	Vdc
Collector–Gate Voltage (R _{GE} = 1.0 MΩ)	VCGR	600	Vdc
Gate-Emitter Voltage — Continuous	VGE	±20	Vdc
Collector Current — Continuous @ T _C = 25°C — Continuous @ T _C = 90°C — Repetitive Pulsed Current (1)	IC25 IC90 ICM	6.0 4.0 8.0	Adc Apk
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	62.5 0.51	Watts W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to 150	°C
Short Circuit Withstand Time (V_{CC} = 400 Vdc, V_{GE} = 15 Vdc, T_J = 125°C, R_G = 20 Ω)	t _{SC}	10	μS
Thermal Resistance — Junction to Case – IGBT — Junction to Case – Diode — Junction to Ambient	R _O JC R _O JA	2.0 3.6 65	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C
Mounting Torque, 6–32 or M3 screw	10 lbf•in (1.13 N•m)		

⁽¹⁾ Pulse width is limited by maximum junction temperature. Repetitive rating.

Designer's Data for "Worst Case" Conditions — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.

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Characteristic		Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS							
Collector–to–Emitter Breakdown Voltage (VGE = 0 Vdc, I _C = 25 μAdc) Temperature Coefficient (Positive)			600 —	 870	_	Vdc mV/°C	
Zero Gate Voltage Collector Current (VCE = 600 Vdc, VGE = 0 Vdc) (VCE = 600 Vdc, VGE = 0 Vdc, TJ = 125°C)		ICES	_	_	10 200	μAdc	
Gate-Body Leakage Current (VGE	= ± 20 Vdc, V _{CE} = 0 Vdc)	IGES	_	_	50	μAdc	
ON CHARACTERISTICS (1)		•	•	•		•	
Collector-to-Emitter On-State Voltage (VGE = 15 Vdc, I _C = 1.5 Adc) (VGE = 15 Vdc, I _C = 1.5 Adc, T _J = 125°C) (VGE = 15 Vdc, I _C = 3.0 Adc)		VCE(on)	_ _ _	1.6 1.5 2.0	1.9 — 2.4	Vdc	
Gate Threshold Voltage (VCE = VGE, IC = 1.0 mAdc) Threshold Temperature Coefficient (Negative)		VGE(th)	4.0 —	6.0 10	8.0 —	Vdc mV/°C	
Forward Transconductance (VCE	= 10 Vdc, I _C = 3.0 Adc)	9fe	_	1.8	_	Mhos	
DYNAMIC CHARACTERISTICS							
Input Capacitance		C _{ies}	_	342		pF	
Output Capacitance	(V _{CE} = 25 Vdc, V _{GE} = 0 Vdc, f = 1.0 MHz)	C _{oes}	_	40	_		
Transfer Capacitance	, ,	C _{res}	_	3.0	_		
SWITCHING CHARACTERISTICS	(1)				-		
Turn-On Delay Time		^t d(on)	_	34	_	ns	
Rise Time		t _r	_	30	_		
Turn-Off Delay Time	$(V_{CC} = 360 \text{ Vdc}, I_{C} = 3.0 \text{ Adc},$	t _d (off)	_	36	_		
Fall Time	V_{GE} = 15 Vdc, L = 300 μH, R_{G} = 20 Ω)	t _f	-	216	_		
Turn-Off Switching Loss	Energy losses include "tail"	E _{off}	-	100	150	μJ	
Turn-On Switching Loss		Eon	-	25	_		
Total Switching Loss	1	E _{ts}	_	125	_]	
Turn-On Delay Time		td(on)	_	33	_	ns	
Rise Time	1	t _r	_	32	_	1	
Turn-Off Delay Time	$(V_{CC} = 360 \text{ Vdc}, I_{C} = 3.0 \text{ Adc},$	t _d (off)	_	56	_	1	
Fall Time	V _{GE} = 15 Vdc, L = 300 μH, R _G = 20 Ω, T _J = 125°C)	t _f	_	340	_	1	
Turn–Off Switching Loss	Energy losses include "tail"	E _{off}	_	170	_	μJ	
Turn-On Switching Loss	1	E _{on}	_	50	_	1	
Total Switching Loss	1	E _{ts}	_	220	_	1	
Gate Charge		QT	_	18.1	_	nC	
	(V _{CC} = 360 Vdc, I _C = 3.0 Adc, V _{GF} = 15 Vdc)	Q ₁	_	3.8	_	1	
vGE = 13 vac)		Q ₂	_	7.8	_	1	

⁽¹⁾ Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

DIODE CHARACTERISTICS

Diode Forward Voltage Drop (I _{EC} = 1.25 Adc) (I _{EC} = 1.25 Adc, T _J = 125°C) (I _{EC} = 2.5 Adc)		VFEC	_ _ _	1.7 1.3 2.0	 2.3	Vdc
Reverse Recovery Time		t _{rr}	_	39	_	ns
	(I _F = 2.5 Adc, V _R = 360 Vdc,	t _a	_	15	_	
	$VR = 300 \text{ Vdc},$ $dI_F/dt = 200 \text{ A/}\mu\text{s})$	t _b	_	24	_	
Reverse Recovery Stored Charge		Q _{RR}	_	51	_	nC
Reverse Recovery Time	/I= - 2.5 Ado	t _{rr}	_	68	_	ns
	(I _F = 2.5 Adc, V _R = 360 Vdc,	t _a	_	21	_	
	$dI_F/dt = 200 \text{ A/}\mu\text{s},$ $T_{.1} = 125^{\circ}\text{C})$	t _b	_	47	_	
Reverse Recovery Stored Charge	13 = 123 0)	Q _{RR}	_	115	_	nC

INTERNAL PACKAGE INDUCTANCE

Internal Emitter Inductance	LE				nΗ
(Measured from the emitter lead 0.25" from package to emitter bond pad)		_	7.5	-	

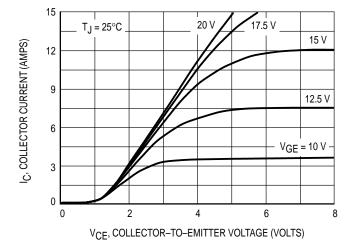


Figure 1. Output Characteristics

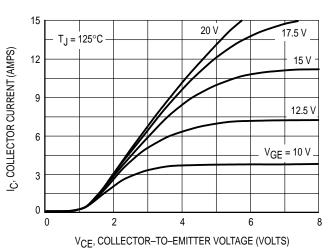


Figure 2. Output Characteristics

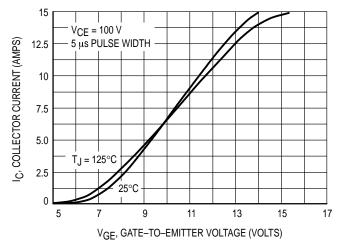


Figure 3. Transfer Characteristics

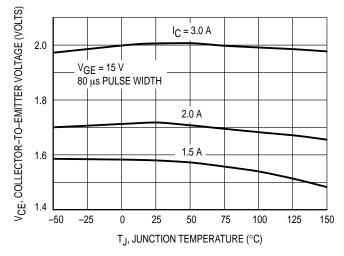


Figure 4. Collector–To–Emitter Saturation Voltage versus Junction Temperature

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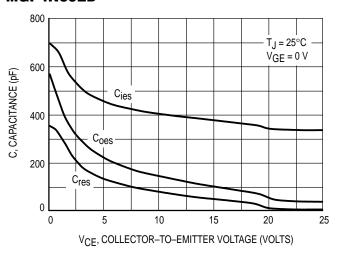


Figure 5. Capacitance Variation

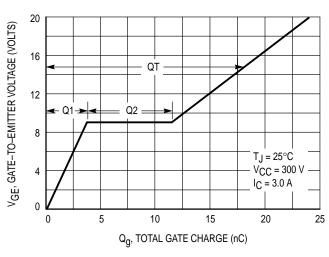


Figure 6. Gate-To-Emitter Voltage versus
Total Charge

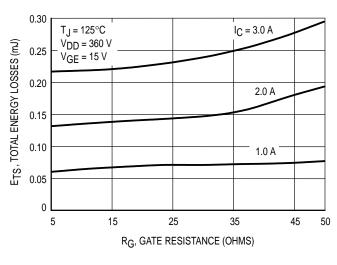


Figure 7. Total Energy Losses versus

Gate Resistance

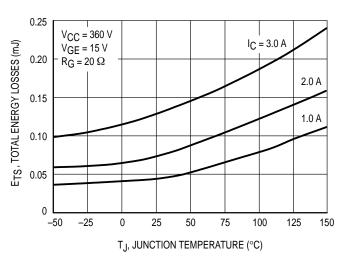


Figure 8. Total Energy Losses versus Junction Temperature

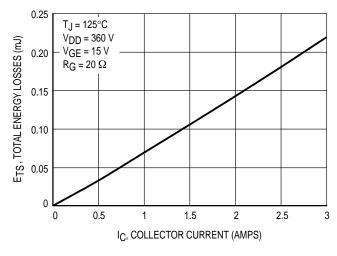


Figure 9. Total Energy Losses versus Collector Current

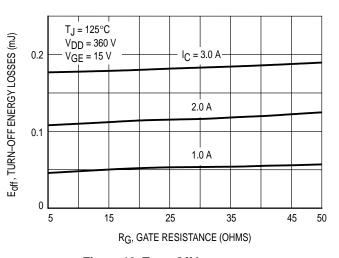


Figure 10. Turn-Off Losses versus
Gate Resistance

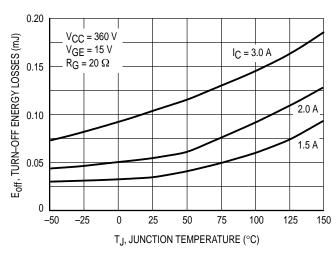


Figure 11. Turn-Off Losses versus Junction Temperature

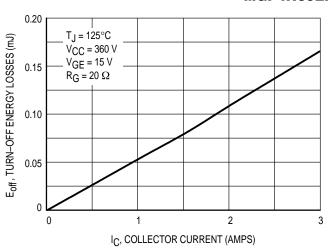


Figure 12. Turn-Off Losses versus Collector Current

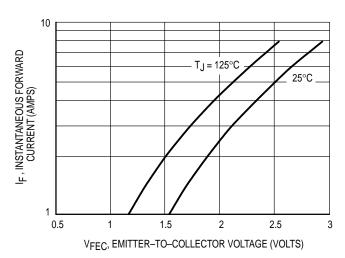


Figure 13. Forward Characteristics versus Current

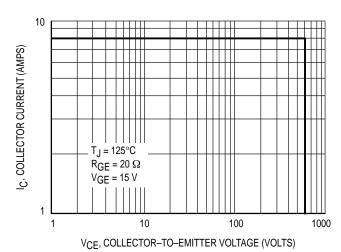
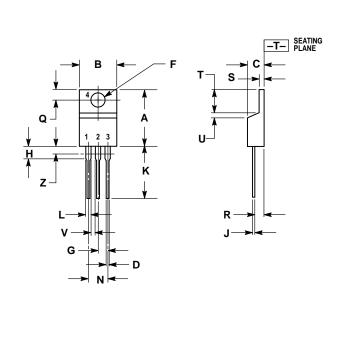


Figure 14. Reverse Biased Safe Operating Area

PACKAGE DIMENSIONS



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INC	INCHES MILLIMI		
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
ø	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z	_	0.080		2.04

STYLE 9:

PIN 1. GATE

COLLECTOR

3. EMITTER

4. COLLECTOR

TO-220AB **ISSUE Z**

CASE 221A-09

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